ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pa	IPC, Bannock	burn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declar the declaration	ration of n encom	the substance the substance the substance	es within t ver level n	he manufactu naterials for v	rer listed it which the m	em. Note anufactur	: if the item is an as rer has engineering	ssembly with low responsibility.		
	IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribut				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mi	ials and Mfg Information				
Supplier Information																
'ompany name*	Company unique ID			Unique ID Authority					Response Date*							
On Semiconductor											2021-02-	2021-02-04				
Contact Name	Title - Conta	Title - Contact			Phone - Contact*					Email -	Email - Contact*					
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com							
Authorized Representative* Title			Title - Representative			Phone - Representative*				Email - Representative*						
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com							
Requester Item Number	Mfr Iter	tem Number Mfr Item Nam		e		Effective Da	ate Ve	e Version Manuf		turing Site	V	Veight*	UOM	Unit Type		
	NC7WZ	216L6X	UHS Dual Buffer			2021-02-04 THB		тнв	ΉB		.086814	mg	Each			
Aanufacturing Proccess Informa	ation					·			1				I	1		
Terminal Plating / Grid Array M	Iaterial '	Terminal Base	Alloy	J-STD-020 MSL Rating		Peak Process Body Tempera		ure Max Time at Peak Tempo		c Temperati	ature Number of Reflow Cycles		cles			
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1		1		260		С	30		second	ls 3				
omments																
evel 1 - maximum time at peak temperat	ture during so	ldering is 10-3	0 seconds													
or more information regarding materia	l composition	please refer to	page 3													

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.04	mg	Supplier	Silicon (Si)	7440-21-3		0.04	mg
Die Attach Tape	0.003	mg		Epoxy resin	proprietary data		0.0006	mg
			Supplier	Acrylic Copolymer	Proprietary Data		0.0005	mg
			Supplier	Filler (SiO2)	68909-20-6		0.0015	mg
			Supplier	Phenolic resins	Proprietary Data		0.0005	mg
Lead Frame	0.802872	mg	Supplier	Mangnesium (Mg)	7439-95-4		0.001	mg
			Supplier	Silicon (Si)	7440-21-3		0.0063	mg
			В	Nickel (Ni)	7440-02-0		0.0261	mg
			Supplier	Copper (Cu)	7440-50-8		0.7695	mg
Mold Compound-Black	1.204	mg		Epoxy resin	proprietary data		0.0602	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0277	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0602	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0048	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0277	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1.0234	mg
Plating	0.024942	mg	Supplier	Silver (Ag)	7440-22-4		0.0001	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0002	mg
			В	Nickel (Ni)	7440-02-0		0.0246	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
Wire Bond	0.012	mg	Supplier	Palladium (Pd)	7440-05-3		0.0002	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0117	mg